12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# # 20240508000.0
Backside Coat removal for select package devices
Information Only

Date: May 09, 2024
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20240508000.0
Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ27427YZFR	NULL
INA216A3YFFR	NULL
LM3644TTYFFR	NULL
LM3648TTYFFR	NULL
OPA2376AIYZDR	NULL
OPA2376AIYZDT	NULL
PGA900AYZST	NULL
TPA2011D1YFFR	NULL
TPA2011D1YFFT	NULL
TPA2038D1YFFR	NULL
TPD1S514-1YZR	NULL
TPS22914CYFPR	NULL
TPS22914CYFPT	NULL
TPS22925CYPHR	NULL
TPS22925CYPHT	NULL
TPS610997YFFR	NULL
TPS610997YFFT	NULL
TPS61099YFFR	NULL
TPS61099YFFT	NULL
TPS61253AYFFR	NULL
TPS61253AYFFT	NULL
TPS6591287YFFR	NULL
TUSB2E111YCGR	NULL

Technical details of this Product Change follow on the next page(s).

Notification Number:	20240508000.0	**Notification Date:**	May 09, 2024
Title:	Backside Coat removal for select package devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Change Type:			

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Materials
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

Notification Details

Description of Change:

This notice is to communicate the removal of backside coat for the devices listed in the product affected section.

Package Device

	Current	Proposed
		
Marking	With Backside Coat	Without Backside Coat

Reason for Change:

Supply continuity

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this notification:

None.

Product Affected:

BCHW12YZS	PTPD1S514-1YZR	TPA2030D1YFFT	TPS61099YFFR
BQ27427YZFR	PTPD1S514-3YZR	TPA2038D1YFFR	TPS61099YFFT
DAN001YZSR	PTPS22914CYFPR	TPA2038D1YFFT	TPS61253AYFFR
INA216A3YFFR	PTPS22925CYPHR	TPD1S514-1YZR	TPS61253AYFFT
LM3644TTYFFR	PTPS6591287YFFR	TPS22914CYFPR	TPS6591287YFFR
LM3648TTYFFR	PTUSB2E112YCGR	TPS22914CYFPT	TUSB2E111YCGR
OPA2376AIYZDR	SN2E111YCGR	TPS22925CYPHR	TUSB2E111YCGT
OPA2376AIYZDT	TPA2011D1YFFR	TPS22925CYPHT	
PGA900AYZSR	TPA2011D1YFFT	TPS610997YFFR	
PGA900AYZST	TPA2030D1YFFR	TPS610997YFFT	

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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